

# LH5316P00B

CMOS 16M (2M × 8/1M × 16) MROM

## FEATURES

- 2,097,152 × 8 bit organization  
(Byte mode:  $\overline{\text{BYTE}} = V_{IL}$ )  
1,048,576 × 16 bit organization  
(Word mode:  $\overline{\text{BYTE}} = V_{IH}$ )
- Access time: 120 ns (MAX.)
- Supply current:
  - Operating: 70 mA (MAX.)
  - Standby: 100  $\mu\text{A}$  (MAX.)
- TTL compatible I/O
- Three-state output
- Single +5 V power supply
- Static operation
- Package:  
44-pin, 600-mil SOP
- Item related with COCOM regulation:
  - Non programmable
  - Not designed or rated as radiation hardened
  - CMOS process (P type silicon substrate)

## DESCRIPTION

The LH5316P00B is a 16M-bit mask-programmable ROM organized as 2,097,152 × 8 bits (Byte mode) or 1,048,576 × 16 bits (Word mode) that can be selected by a BYTE input pin. It is fabricated using silicon-gate CMOS process technology.

## PIN CONNECTIONS

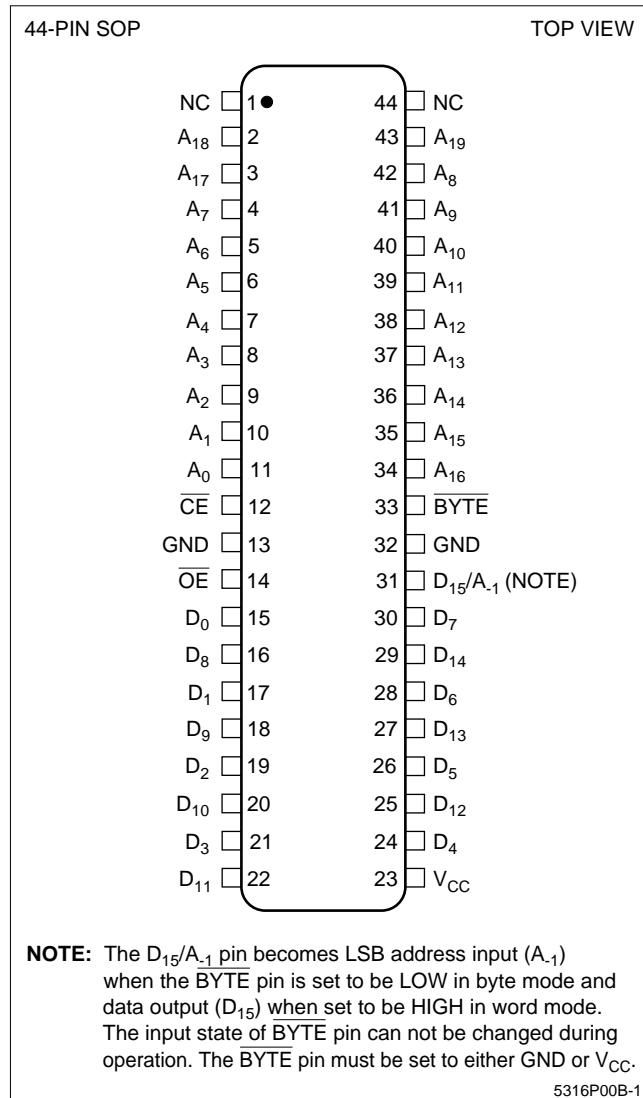


Figure 1. Pin Connections

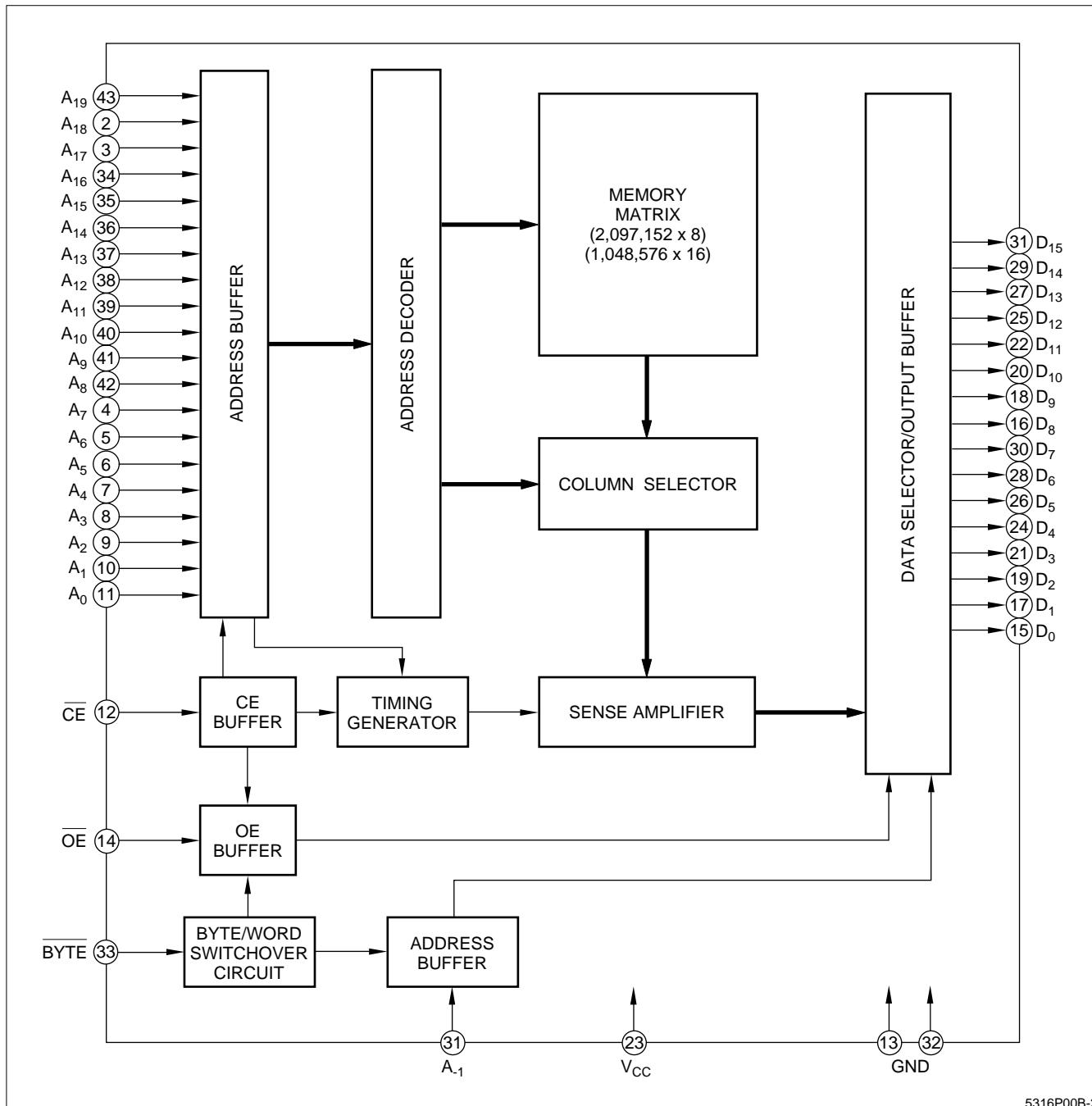


Figure 2. LH5316P00B Block Diagram

**PIN DESCRIPTION**

SIGNAL	PIN NAME
A <sub>-1</sub> - A <sub>19</sub>	Address input
D <sub>0</sub> - D <sub>15</sub>	Data output
BYTE	x8bit / x16 bit (Byte/word) mode select input
CE	Chip enable input

SIGNAL	PIN NAME
OE	Output enable input
V <sub>CC</sub>	Power supply
GND	Ground
NC	No connection

**TRUTH TABLE**

<b><math>\overline{CE}</math></b>	<b><math>\overline{OE}</math></b>	<b>BYTE</b>	<b>A-1 (D<sub>15</sub>)</b>	<b>DATA OUTPUT</b>		<b>ADDRESS INPUT</b>		<b>SUPPLY CURRENT</b>
				<b>D<sub>0</sub> - D<sub>7</sub></b>	<b>D<sub>8</sub> - D<sub>15</sub></b>	<b>LSB</b>	<b>MSB</b>	
H	X	X	X	High-Z	High-Z	—	—	Standby ( $I_{SB}$ )
L	H	X	X	High-Z	High-Z	—	—	Operating
L	L	H	—	D <sub>0</sub> - D <sub>7</sub>	D <sub>8</sub> - D <sub>15</sub>	A <sub>0</sub>	A <sub>19</sub>	Operating
L	L	L	L	D <sub>0</sub> - D <sub>7</sub>	High-Z	A <sub>-1</sub>	A <sub>19</sub>	Operating
L	L	L	H	D <sub>8</sub> - D <sub>15</sub>	High-Z	A <sub>-1</sub>	A <sub>19</sub>	Operating

**NOTES:**

X = Don't care; High-Z = High-impedance

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	RATING		UNIT
Supply voltage	$V_{CC}$	-0.3 to +7.0		V
Input voltage	$V_{IN}$	-0.3 to $V_{CC}$ + 0.3		V
Output voltage	$V_{OUT}$	-0.3 to $V_{CC}$ + 0.3		V
Operating temperature	$T_{OPR}$	0 to +70		°C
Storage temperature	$T_{STG}$	-65 to +150		°C

**RECOMMENDED OPERATING CONDITIONS ( $T_A = 0$  to  $+70^\circ\text{C}$ )**

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage	$V_{cc}$	4.5	5.0	5.5	V

**DC ELECTRICAL CHARACTERISTICS ( $V_{CC} = 5$  V  $\pm 10\%$ ,  $T_A = 0$  to  $+70^\circ\text{C}$ )**

PARAMETER	SYMBOL	CONDITIONS	MIN.	MAX.	UNIT	NOTE
Input 'High' voltage	$V_{IH}$	—	2.2	$V_{CC}$ + 0.3	V	—
Input 'Low' voltage	$V_{IL}$	—	-0.3	0.8	V	—
Output 'High' voltage	$V_{OH}$	$I_{OH} = -400 \mu\text{A}$	2.4	—	V	—
Output 'Low' voltage	$V_{OL}$	$I_{OL} = 2.0 \text{ mA}$	—	0.4	V	—
Input leakage current	$I_{LI}$	$V_{IN} = 0 \text{ V}$ to $V_{CC}$	—	10	$\mu\text{A}$	—
Output leakage current	$I_{LO}$	$V_{OUT} = 0 \text{ V}$ to $V_{CC}$	—	10	$\mu\text{A}$	1
Operating current	$I_{CC1}$	$t_{RC} = 120 \text{ ns}$	—	70	mA	2
	$I_{CC2}$	$t_{RC} = 1 \mu\text{s}$	—	55		
Standby current	$I_{SB1}$	$CE = V_{IH}$	—	2	mA	—
	$I_{SB2}$	$CE = V_{CC} - 0.2 \text{ V}$	—	100	$\mu\text{A}$	—
Input capacitance	$C_{IN}$	$f = 1 \text{ MHz}, t_A = 25^\circ\text{C}$	—	10	pF	—
Output capacitance	$C_{OUT}$		—	10	pF	—

**NOTES:**

1.  $CE = V_{IH}$ ,  $OE = V_{IH}$ , output is open
2.  $V_{IN} = V_{IH}$ ,  $V_{IL}$ ,  $CE = V_{IL}$ , output is open

**AC ELECTRICAL CHARACTERISTICS (V<sub>CC</sub> = 5 V ±10%, T<sub>A</sub> = 0 to +70°C)**

PARAMETER	SYMBOL	MIN.	MAX.	UNIT	NOTE
Read cycle time	t <sub>RC</sub>	120	—	ns	—
Address access time	t <sub>AA</sub>	—	120	ns	—
Chip enable access time	t <sub>ACE</sub>	—	120	ns	—
Output enable delay time	t <sub>OE</sub>	—	60	ns	—
Output hold time	t <sub>OH</sub>	5	—	ns	—
Output floating time	t <sub>CHZ</sub>	—	60	ns	1
	t <sub>OHZ</sub>	—	60	ns	

**NOTE:**

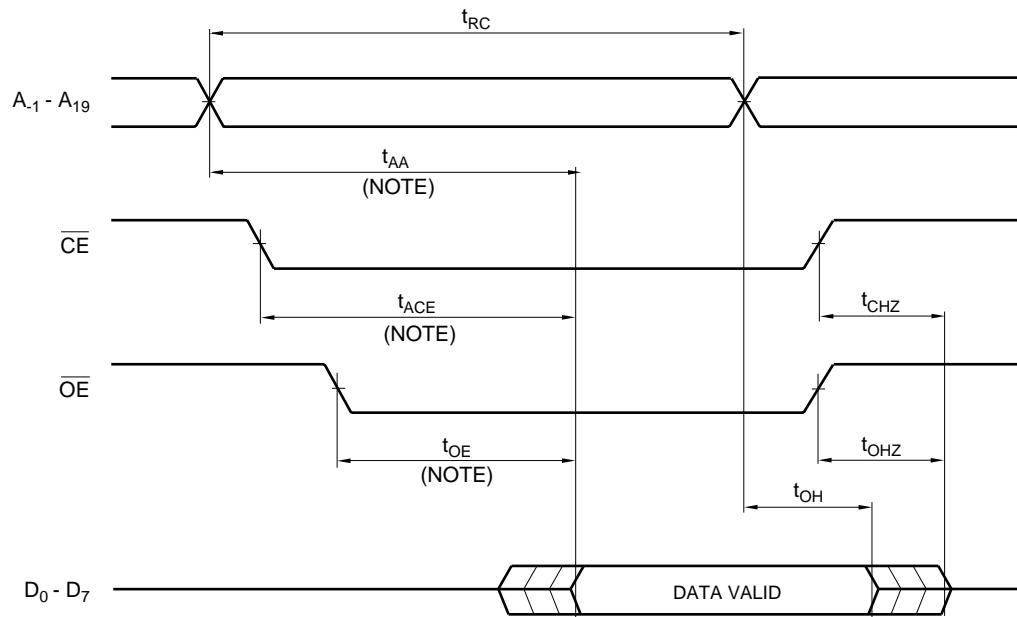
1. Determined by the time for the output to be opened. (Irrespective of output voltage)

**AC TEST CONDITIONS**

PARAMETER	RATING
Input voltage amplitude	0.6 V to 2.4 V
Input rise/fall time	10 ns
Input signal fall time	10 ns
Input reference level	1.5 V
Output reference level	1.5 V
Output load condition	1TTL + 100 pF

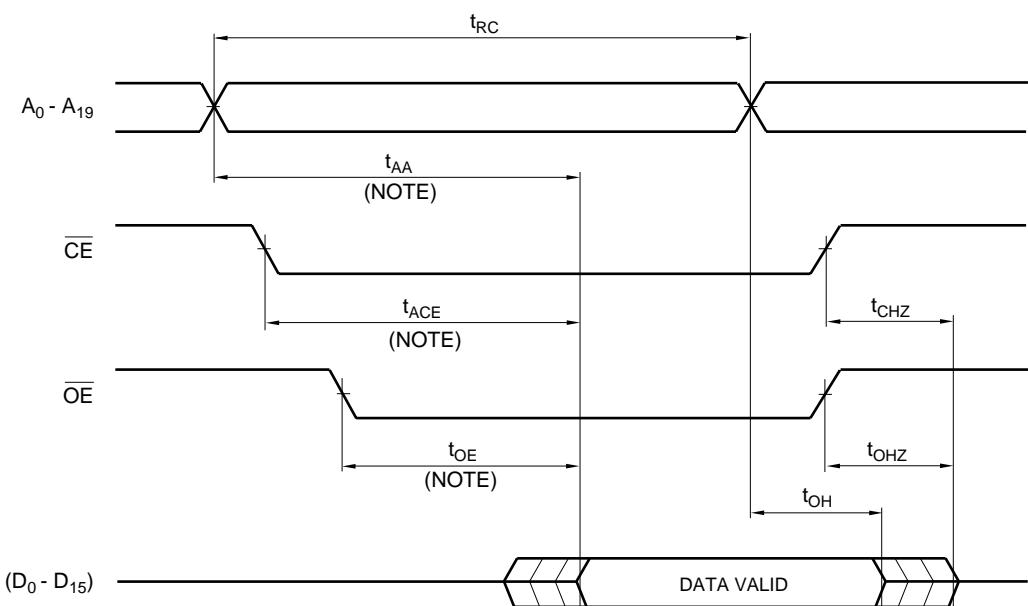
**CAUTION**

It is recommended that a decoupling capacitor be connected between V<sub>CC</sub> and GND-Pin.



**NOTE:** The output data becomes valid when the last intervals,  $t_{AA}$ ,  $t_{ACE}$ , or  $t_{OE}$ , have concluded.

5316P00B-3

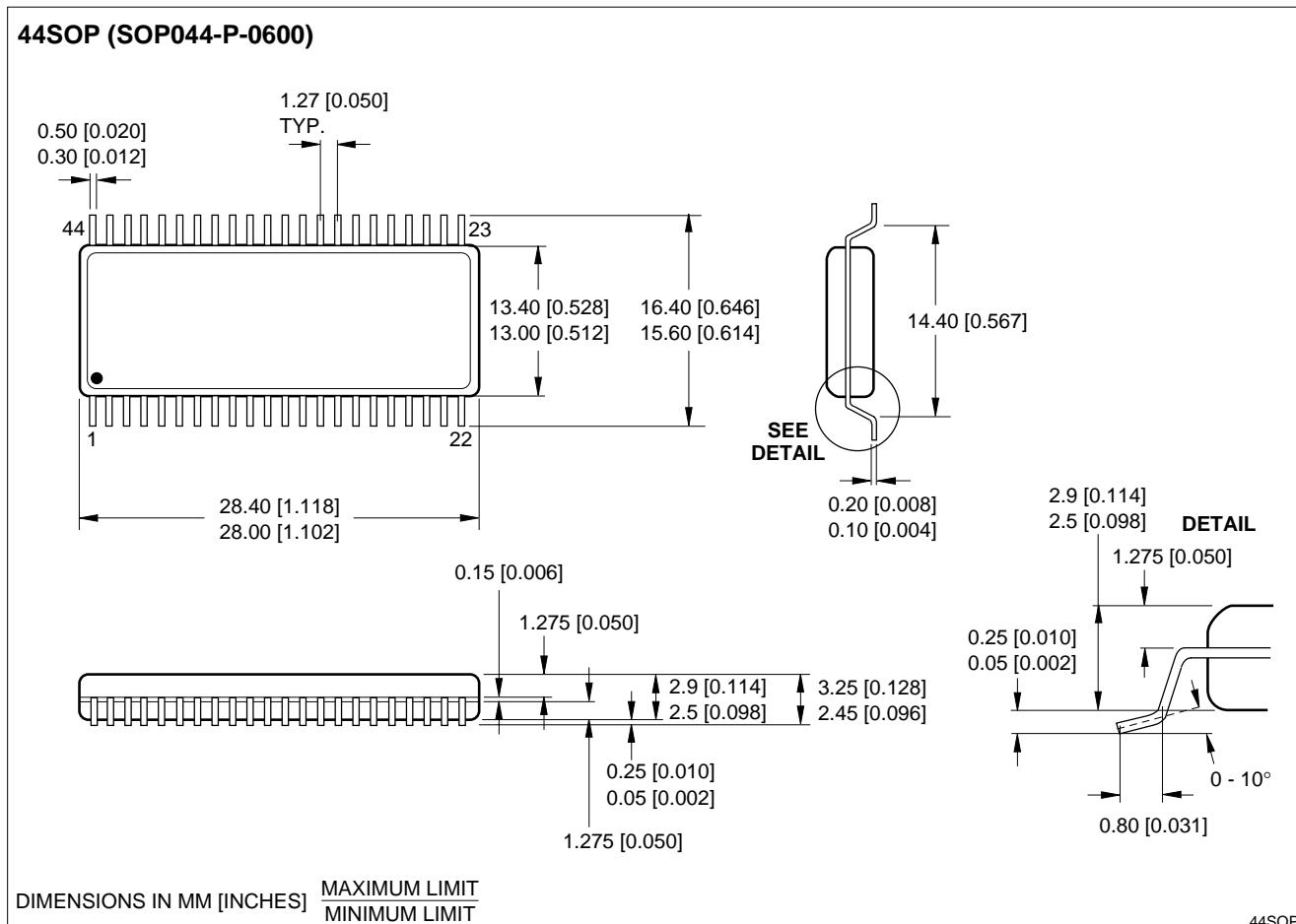
Figure 3. Byte Mode (BYTE = V<sub>IL</sub>)

**NOTE:** The output data becomes valid when the last intervals,  $t_{AA}$ ,  $t_{ACE}$ , or  $t_{OE}$ , have concluded.

5316P00B-4

Figure 4. Word Mode (BYTE = V<sub>IH</sub>)

## PACKAGE DIAGRAM



## ORDERING INFORMATION

LH5316P00B  
Device Type

N  
Package

44-pin, 600-mil SOP (SOP044-P-600)

CMOS 16M (2M x 8 or 1M x 16) Mask-Programmable ROM

**Example:** LH5316P00N (CMOS 16M (2M x 8 or 1M x 16) Mask-Programmable ROM, 44-pin, 600-mil SOP)

5316P00B-5